

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Douglas M. Reber</td> <td>09/25/2013</td> </tr> <tr> <td>Mehul D. Shroff</td> <td>09/25/2013</td> </tr> <tr> <td>Edward O. Travis</td> <td>09/25/2013</td> </tr> </tbody> </table>		Name	Execution Date	Douglas M. Reber	09/25/2013	Mehul D. Shroff	09/25/2013	Edward O. Travis	09/25/2013
Name	Execution Date								
Douglas M. Reber	09/25/2013								
Mehul D. Shroff	09/25/2013								
Edward O. Travis	09/25/2013								
RECEIVING PARTY DATA									
Name:	FREESCALE SEMICONDUCTOR, INC.								
Street Address:	6501 William Cannon Drive								
Internal Address:	MD: TX30/OE62								
City:	Austin								
State/Country:	Texas								
Postal Code:	78735								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14039622</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14039622				
Property Type	Number								
Application Number:	14039622								
CORRESPONDENCE DATA									
Fax Number:	5123551119								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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ATTORNEY DOCKET NUMBER:	1080-MT12436TK								
NAME OF SUBMITTER:	Ryan S. Davidson								
Signature:	/Ryan S. Davidson/								

CH \$40.00 14039622

PATENT

Date:

09/27/2013

Total Attachments: 6

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PATENT

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, **DOUGLAS M. REBER** of Austin, Texas; **MEHUL D. SHROFF** of Austin, Texas; and **EDWARD O. TRAVIS** of Austin, Texas, have sold, assigned and transferred, and do hereby sell, assign and transfer, unto **FREESCALE SEMICONDUCTOR, INC.**, a corporation of the State of Delaware, having its principal office in Austin, State of Texas, United States of America, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions relating to improvements in **3D DEVICE PACKAGING USING THROUGH-SUBSTRATE PILLARS** (Docket No. 1080-MT12436TK), described, illustrated and claimed in an application for Letters Patent of the United States of America executed by us on the dates indicated by our signatures below, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation or reissue thereof.

We hereby also sell, assign and transfer unto **FREESCALE SEMICONDUCTOR, INC.**, the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and we further authorize **FREESCALE SEMICONDUCTOR, INC.** to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to **FREESCALE SEMICONDUCTOR, INC.**, for the sole use and benefit of **FREESCALE SEMICONDUCTOR, INC.**, its successors, assigns and legal representatives, to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to **FREESCALE SEMICONDUCTOR, INC.**

We agree that, when requested, we will, without charge to **FREESCALE SEMICONDUCTOR, INC.**, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in **FREESCALE SEMICONDUCTOR, INC.**, its successors, assigns and legal representatives or nominees.

PATENT

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